

SolderStar PRO - Reflow Profiling Solutions

solderstar
www.solderstar.com

Featuring SolderStar

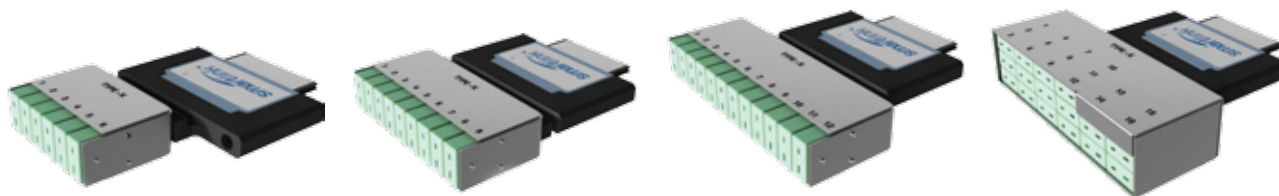
smartlink
connection System



Smartlink Thermal Barrier Concept
(9 Channel Version Pictured)



Miniature Profiling Datalogger



Thermocouple Adapters available in 6,9,12 or 16 Channel versions

Reflow Profiling upto 16 Measurement Channels

The package includes an ultra compact datalogger featuring the unique 'SmartLink' connector system, combined with a heatshield and thermocouple adapter to provide the number of measurement channels required.

Future upgrading or servicing is a simple and cost effective procedure, with only the Thermocouple Adapter needing to be changed to allow 6,9,12 or 16 Type-K measurement versions.

The 'SmartLink' concept allows high measurement channel configurations, while maintaining a small footprint and quick connection to a range of accessories for capture of profile and SPC information from reflow, wave/selective and vapour phase soldering processes.

A comprehensive suite of software includes profile analysis, data management, profile simulations and integrated SPC charting tools. This easy to use system is ideal for manufacturers and EMS providers who require rapid profile setup followed by periodic measurements to control their solder process quality.

System Advantages

- Compact size for profiling of narrow PCB formats or ovens with low tunnel clearance
- Support for 6 to 16 measurement channels for profiling of the most complex PCB assemblies
- Unique SmartLink connection system provides quick datalogger connection to a range of products and accessories
- Software tools including profile analysis and simulation, plus integrated SPC management features
- Connectivity via standard USB cables or 2.4Ghz Wireless Telemetry
- Extendable for control of wave / selective or vapour phase soldering

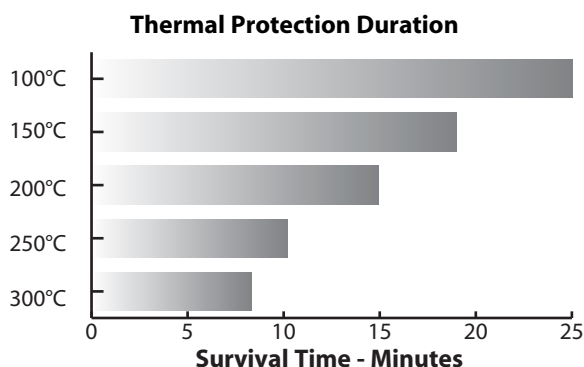
Datalogger

Technical Data

Size/Weight	125mm x 52mm x 9mm, 110g
Channels	6,9,12 or 16 Channel Versions Available
Memory	120,000 Memory Points
Sampling	0.1s to 10 Minutes
Measurement Range	-150 to 600 °C
Accuracy	±1 °C
Resolution	±0.02 °C
Max. Internal Temperature	+85 °C (Auto Shutdown on over temp.)
Power	Rechargeable High Temperature Nimh
Communications	USB (Type A - Mini B) or 2.4Ghz Wireless
Thermocouples	Type K, EN 05842:1993 Class 1 / ANSI MC 96.1

Heatshield

Material	Stainless Steel
Size (LxWxH)	6/9 Channel Version: 310mm x 80mm x 25mm 12 Channel Version: 310mm x 104mm x 25mm 16 Channel Version: 330mm x 146mm x 25mm



Wireless Telemetry Option

Frequency	2.4GHZ Transceiver
Channels	128 Individual Channels
Protocol	Zigbee PRO - Duplex Transmission



Software

Compatibility	Windows™ XP Vista/Windows 7/8 32 & 64 Bit
Language Support	English, French, German, Italian, Portuguese, Spanish & Chinese

Standard Equipment

- SolderStar PRO datalogger
- Thermocouple Adapter
- 25mm Lead Free capable heatshield
- Type K thermocouples
- PC Analysis software
- Hard copy manual + 1 Year calibration certificate
- Equipment case

Optional Reflow Equipment

- AUTOSseeker Profiler Optimisation software
- 2.4Ghz Wireless Telemetry
- Deltaprobe Oven Verification fixture
- Adjustable Reflow Carrier

Additional Process Support



REFLOW • WAVE • VAPOUR

A range of process specific accessories are available to extend the system for use with Reflow, Wave/Selective Soldering and Vapour Phase processes.